



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21C101JBANFNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 100 pF, 50V, ±5%, C0G, 0805

A. Samsung Part Number

<u>CL</u> <u>21</u> <u>C</u> <u>101</u> <u>J</u> <u>B</u> <u>A</u> <u>N</u> <u>F</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Seri	es Samsung M	Samsung Multi-layer Ceramic Capacitor					
② Size	e 0805 (in	ch code) L: 2	2.0 ±	: 0.1 mı	m W:	1.25 ± 0.1	mm
3 Diel	ectric C0G	(B) li	nner electr	ode	Ni	
4 Cap	acitance 100 pF		Т	- ermination	า	Cu	
⑤ Сар	acitance ±5 %		P	Plating		Sn 100%	(Pb Free)
tole	rance	(9	9 P	Product		Product for P	OWER application
6 Rate	ed Voltage 50 V	Q	0 S	Special		Reserved for	future use
7 Thio	kness 0.65 ± 0).1 mm (1	D P	Packaging		Cardboard Ty	pe, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition				
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms				
Q	1000 min					
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.				
Resistance	Whichever is Smaller					
Appearance	No abnormal exterior appearance	Microscope (×10)				
Withstanding	No dielectric breakdown or	300% of the rated voltage				
Voltage	mechanical breakdown					
Temperature	COG					
Characterisitcs	(From -55℃ to 125℃, Capacitance change shoud be within ±30PPM/℃)					
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.				
of Termination	terminal electrode					
Bending Strength	Capacitance change :	Bending to the limit (1mm)				
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.				
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder				
	is to be soldered newly	245±5℃, 3±0.3sec.				
		(preheating : 80~120 ℃ for 10~30sec.)				
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.				
Soldering heat	within ±2.5% or ±0.25pF whichever is larger					
	Tan δ, IR : initial spec.					

	Performance	Test condition			
Vibration Test	Capacitance change :	Amplitude : 1.5mm			
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)			
	Tan δ, IR : initial spec.	2hours \times 3 direction (x, y, z)			
Moisture	Capacitance change :	With rated voltage			
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs			
	Q: 200 min				
	IR : 500Mohm or 25Mohm $\cdot \mu$ F				
	Whichever is Smaller				
High Temperature	Capacitance change :	With 200% of the rated voltage			
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature			
	Q: 350 min	1000+48/-0hrs			
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F				
	Whichever is Smaller				
Temperature	Capacitance change :	1 cycle condition			
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperature $ ightarrow$ 25 $^{\circ}$ C			
	Tan δ, IR : initial spec.	$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!$			
		5 cycle test			

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C , 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.